

**DynaStrip™ DL7630**

- Removes photoresist and post-etch residue from dry metal etch processes
- Dissolves negative photoresist in solder bumping processes
- For use in single-wafer clean processes

**DynaStrip™ DL88**

- Formulated to strip positive photoresist from metals that are sensitive to corrosion
- DynaStrip DL88 is completely water rinsable.
- Effective for flux residue removal
- Batch spray processing

**DynaStrip™ DL8800**

- Designed to strip positive photoresist
- Exceptionally low metal etch rates
- Contains no NMP, DMSO, TMAH, or hydroxylamine

**DynaStrip™ DL9150**

- Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
- Improved EH&S footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance

**DynaStrip™ DL9150B**

- Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
- Improved EH&S footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance
- Improved Cu compatibility

**DynaStrip™ DL9240**

- Green technology for photoresist removal
- Improved EH&S footprint; formulation contains no DMSO and no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); removes negative dry-film resist

**FlipStrip™**

- For removal of negative dry-film photoresists that are difficult to remove due to high-temperature reflow process
- Compatible with Cu, Al, and most polyimide (PI)
- Very high loading capacity of photoresist
- Greater than a 72-hour bath life

**Dynasolve 219**

- For removal of temporary adhesive materials in applications where a better penetrating solvent is required due to a smaller exposed surface area
- Quick dissolving of silicone-based adhesives

**Dynasolve FS8320**

- Designed specifically for removing flux after solder reflow process
- Cleans rosin, no-clean, and water soluble flux

**Dynasolve PI4310**

- Proven solution for removal or rework of PI dielectric layers
- Removes PI through various process stages from coat through post-develop bake process

**EH&S (environmental, health, and safety) advantaged—product does not contain any of the following materials:**

- Tetramethyl ammonium hydroxide (TMAH)
- Hydroxylamine (HA)
- Dimethylsulfoxide (DMSO)
- *N*-methylpyrrolidone (NMP)



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# Photoresist and residue removers

